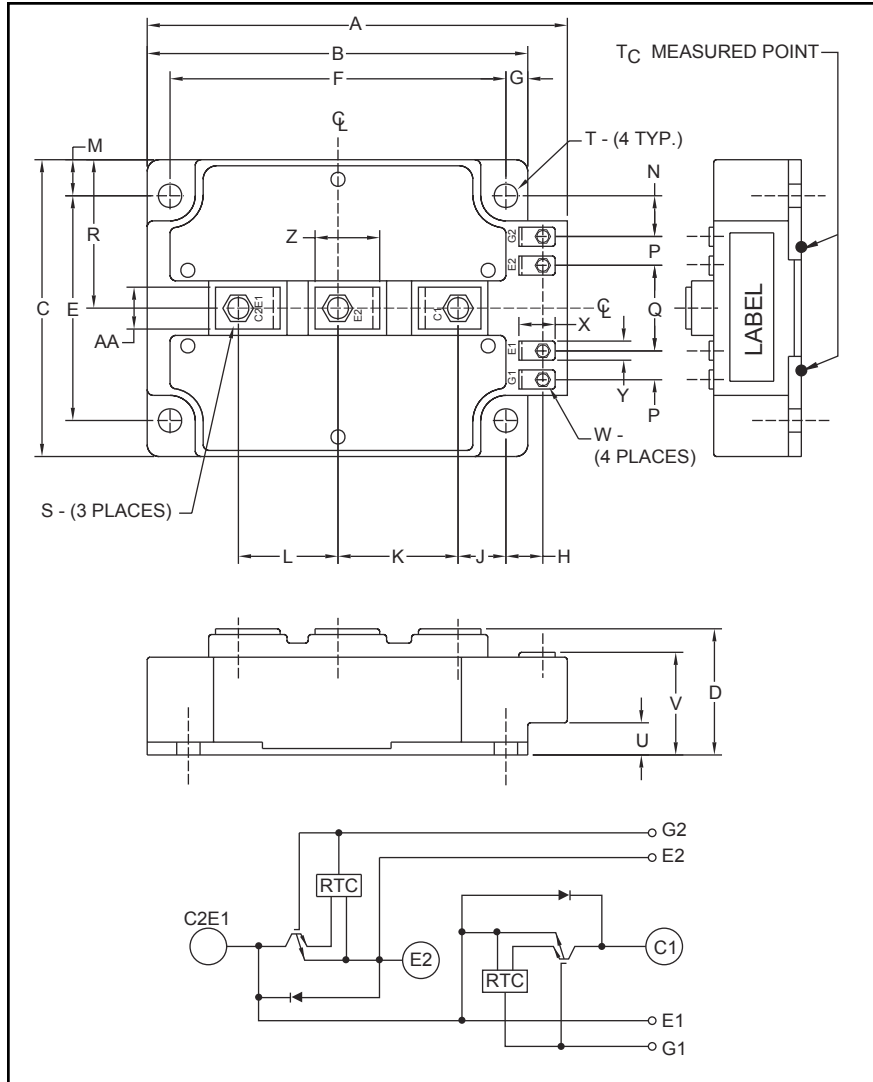


Dual IGBTMOD™ F-Series Module 400 Amperes/1200 Volts



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	5.51	140.0
B	5.12	130.0
C	5.12	130.0
D	1.38 +0/-0.02	35.0 +0/-0.5
E	4.33±0.01	110.0±0.25
F	4.33±0.01	110.0±0.25
G	0.39	10.0
H	0.45	11.5
J	0.54	13.8
K	1.72	43.8
L	1.42	36.0
M	0.39	10.0
N	0.80	20.4

Dimensions	Inches	Millimeters
P	0.57	14.5
Q	1.57	40.0
R	2.56	65.0
S	M8	M8
T	0.32	8.0
U	0.32	8.0
V	0.97 +0.04/-0.02	24.5 +1.0/-0.5
W	M4	M4
X	0.59	15.0
Y	0.35	9.0
Z	1.02	26.0
AA	0.79	20.0



Description:

Powerex IGBTMOD™ Modules are designed for use in switching applications. Each module consists of two IGBT Transistors in a half-bridge configuration with each transistor having a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:

- ☐ Low Drive Power
- ☐ Low $V_{CE(sat)}$
- ☐ Discrete Super-Fast Recovery Free-Wheel Diode
- ☐ Isolated Baseplate for Easy Heat Sinking

Applications:

- ☐ AC Motor Control
- ☐ Motion/Servo Control
- ☐ UPS
- ☐ Welding Power Supplies
- ☐ Laser Power Supplies

Ordering Information:

Example: Select the complete module number you desire from the table - i.e. CM400DU-24F is a 1200V (V_{CES}), 400 Ampere Dual IGBTMOD™ Power Module.

Type	Current Rating Amperes	V_{CES} Volts (x 50)
CM	400	24

CM400DU-24F

Dual IGBTMOD™ F-Series Module

400 Amperes/1200 Volts

Absolute Maximum Ratings, $T_j = 25^\circ\text{C}$ unless otherwise specified

Ratings	Symbol	CM400DU-24F	Units
Junction Temperature	T_j	-40 to 150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to 125	$^\circ\text{C}$
Collector-Emitter Voltage (G-E SHORT)	V_{CES}	1200	Volts
Gate-Emitter Voltage (C-E SHORT)	V_{GES}	± 20	Volts
Collector Current ($T_c = 25^\circ\text{C}$)	I_c	400	Amperes
Peak Collector Current	I_{CM}	800*	Amperes
Emitter Current** ($T_c = 25^\circ\text{C}$)	I_E	400	Amperes
Peak Emitter Current**	I_{EM}	800*	Amperes
Maximum Collector Dissipation ($T_c = 25^\circ\text{C}$, $T_j \leq 150^\circ\text{C}$)	P_c	1100	Watts
Mounting Torque, M8 Main Terminal	–	95	in-lb
Mounting Torque, M6 Mounting	–	40	in-lb
G(E) Terminal, M4	–	15	in-lb
Weight	–	1200	Grams
Isolation Voltage (Main Terminal to Baseplate, AC 1 min.)	V_{iso}	2500	Volts

Static Electrical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	I_{CES}	$V_{\text{CE}} = V_{\text{CES}}$, $V_{\text{GE}} = 0\text{V}$	–	–	2	mA
Gate Leakage Voltage	I_{GES}	$V_{\text{GE}} = V_{\text{CES}}$, $V_{\text{CE}} = 0\text{V}$	–	–	80	μA
Gate-Emitter Threshold Voltage	$V_{\text{GE(th)}}$	$I_c = 40\text{mA}$, $V_{\text{CE}} = 10\text{V}$	5.0	6	7.0	Volts
Collector-Emitter Saturation Voltage	$V_{\text{CE(sat)}}$	$I_c = 400\text{A}$, $V_{\text{GE}} = 15\text{V}$, $T_j = 25^\circ\text{C}$	–	1.8	2.4	Volts
		$I_c = 400\text{A}$, $V_{\text{GE}} = 15\text{V}$, $T_j = 125^\circ\text{C}$	–	1.9	–	Volts
Total Gate Charge	Q_G	$V_{\text{CC}} = 600\text{V}$, $I_c = 400\text{A}$, $V_{\text{GE}} = 15\text{V}$	–	4400	–	nC
Emitter-Collector Voltage**	V_{EC}	$I_E = 400\text{A}$, $V_{\text{GE}} = 0\text{V}$	–	–	3.2	Volts

* Pulse width and repetition rate should be such that the device junction temperature (T_j) does not exceed $T_{j(\text{max})}$ rating.

**Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDI).

CM400DU-24F
Dual IGBTMOD™ F-Series Module
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Dynamic Electrical Characteristics, $T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified

Characteristics		Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance		C _{ies}		—	—	160	nf
Output Capacitance		C _{oes}	V _{CE} = 10V, V _{GE} = 0V	—	—	6.8	nf
Reverse Transfer Capacitance		C _{res}		—	—	4	nf
Resistive	Turn-on Delay Time	t _{d(on)}	V _{CC} = 600V, I _C = 400A,	—	—	450	ns
Load	Rise Time	t _r	V _{GE1} = V _{GE2} = 15V,	—	—	200	ns
Switch	Turn-off Delay Time	t _{d(off)}	R _G = 3.1Ω,	—	—	1000	ns
Times	Fall Time	t _f	Inductive Load	—	—	300	ns
Diode Reverse Recovery Time*		t _{rr}	Switching Operation	—	—	550	ns
Diode Reverse Recovery Charge*		Q _{rr}	I _E = 400A	—	23.6	—	μC

Thermal and Mechanical Characteristics, $T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)Q}$	Per IGBT 1/2 Module, T_C Reference Point per Outline Drawing	—	—	0.11	$^{\circ}\text{C/W}$
Thermal Resistance, Junction to Case	$R_{th(j-c)R}$	Per FWDi 1/2 Module, T_C Reference Point per Outline Drawing	—	—	0.13	$^{\circ}\text{C/W}$
Thermal Resistance	$R_{th(j-c')Q}$	Per IGBT 1/2 Module T_C Reference Point Under Chips	—	—	0.045**	$^{\circ}\text{C/W}$
Contact Thermal Resistance	$R_{th(c-f)}$	Per Module, Thermal Grease Applied	—	0.010	—	$^{\circ}\text{C/W}$

*Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

**If you use this value, $R_{th(f-a)}$ should be measured just under the chips.

CM400DU-24F

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